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TITLE

U.S. **UTILITY** Patent Application O.I.P.E.

SCANNED C

PATENT DATE

APPLICATION NO. CONT/PRIOR CLASS SUBCLASS 09/817473 ART UNIT EXAMINER , D 438 63 2813 THANH NEWY Yi Xu Jia Zheng Jane Hui Charles Lin

Gap filling process in integrated circuits using low dielectric constant materials

(Attached in pocket on right inside flap)

			ISSUING C	LASSIFICATION	11)			
ORIGINAL		CROSS REFERENCE(S)						
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TERMINAL	DRAWINGS			CLAIMS ALLOWED	
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☐ The term of this patent subsequent to (date).			NOTICE OF ALLOWANCE MAILED		
has been disclaimed.	(Assistant Examiner) (Date)				
The term of this patent shall not extend beyond the expiration date			i en	.*1	
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